

Electronic Patent Application Fee Transmittal

Application Number:	10719020			
Filing Date:	24-Nov-2003			
Title of Invention:	Method for preparing a circuit board material having a conductive base and a resistance layer			
First Named Inventor/Applicant Name:	Akira Matsuda			
Filer:	Shuji Yoshizaki/Maya Takakura			
Attorney Docket Number:	032130			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810